

Applicant : Yoshinori Hino et al.  
Serial No. : 10/076,154  
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142893M/KJK

Amendments to the Specification:

Please replace the title beginning at page 1, line 1 with the following amended title:

SEMICONDUCTOR DEVICE ~~AND MANUFACTURING METHOD THEREOF~~  
WITH SMOOTHED PAD PORTION

Please replace the paragraph beginning at page 23, line 1 with the following amended paragraph:

Then, a gold bump electrode 63 is formed at a pad portion 64 formed by opening a passivation film 62 on the third layer wiring 61 extended to separated region from the region forming the via hole 60.